

#### High-performance Video Signal Switchers

# Ultra Wide Band Triple Circuits Video Signal Switchers



**BA7657F,BH7659FS**No.11066EAT03

#### Description

The BA7657F, and BH7659FS are ICs that have been developed for use in PC monitors, HDTVs (high definition televisions), and other high-resolution display devices. In addition to their wide-range switching circuits for RGB signals, HD signals, and VD signals, the A7657F feature a separation (BUNRI) circuit for the synchronization signal that is superposed on the G signal, while the BH7659FS features an on-chip switch for I<sup>2</sup>C bus signals (SDA and SCL). These ICs can be used to simplify the input block configuration in advanced display devices.

#### Features

- 1) Operates on 5 V single power supply.
- 2) Built-in wide-range RGB signal switches. (BA7657F :fc = 230 MHz) (BH7659FS:fc = 250 MHz)
- 3) Built-in switching circuit for HD signal and VD signal.
- 4) Built-in separation (BUNRI) circuit for synchronization signal superposed on G signal. (BA7657F)
- 5) Built-in switch for I<sup>2</sup>C bus signals (SDA and SCL). (BH7659FS)
- 6) Built-in power saving function. (BH7659FS)

#### Applications

PC monitors, Plasma displays, LCD monitors, and Other devices that use wide-range RGB signal switching.

#### Line up matrix

Parameter	BA7657F	BH7659FS
Circuit current (mA)	35	25
Circuit current during low-power mode (mA)	_	14
RGB signal SW block frequency characteristics (MHz)	230	250
Synchronization signal SW block circuit configuration	2 digital switching circuits	4 CMOS analog switching circuits
Synchronization signal separation circuit	<b>✓</b>	_
Package	SOP24	SSOP-A32

#### ●Absolute Maximum Ratings(Ta=25°C)

Parameter		Symbol	Ratings	Unit
Supply voltage		Vcc	8.0	V
Dower dissination	BA7657F	Pd	550	mW
Power dissipation	BH7659FS	Fu	800	IIIVV
Operating temperature		Topr	-25~+75	°C
Storage temperature		Tstg	-55~+125	°C

<sup>\*\*</sup>Deratings is done at 5.5mW/°C (BA7657F), 8mW/°C (BA7659FS) above Ta=25°C.

#### ●Operating Range(Ta=25°C)

Parameter	Symbol		Unit		
Faianielei	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Vcc	4.5	5.0	5.5	V

<sup>\*</sup>This product is not designed for protection against radioactive rays.

#### Electrical characteristics

OBA7657F(Unless otherwise noted, Ta=25°C, Vcc=5.0V)

OBA7657F(Unless otherwise noted,			Limits		1.1-20	O Pro
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Circuit current	ICC	20	35	50	mA	_
⟨Analog SW block⟩						
Maximum output level	Vom	2.8	_	_	VP-P	f=1kHz
Voltage gain	Gv	-1.0	-0.5	0	dB	f=1MHz,VIN=1VP-P
Input pin voltage gain differential	ΔGVI	-0.2	0	0.2	dB	f=1MHz,VIN=1VP-P
Inter block voltage gain differential	Gvв	-0.2	0	0.2	dB	f=1MHz,VIN=1VP-P
Input pin cross talk1	CTI1	_	-50	-40	dB	f=10MHz,VIN=1VP-P
Interblock crosstalk1	CTB1	_	-50	-40	dB	f=10MHz,VIN=1VP-P
⟨Digital SW block⟩						
"H" level input voltage	VIH	1.8	_	_	V	_
"L" level input voltage	VIL	_	_	1.2	V	_
"H" level input current	lін	80	100	130	μΑ	VIN=5.0V
"L" level input current	lı∟	-3	-1	_	μA	VIN=0V
Rise time	TR	_	30	50	ns	_
Fall time	TF	_	30	50	ns	_
Rise delay time	TRD	_	50	80	ns	_
Fall delay time	TFD	_	30	50	ns	_
"H" level output voltage	Vон	3.0	3.7	_	V	_
"L" level output voltage	Vol	_	0.2	0.4	V	_
"H" level output current	Іон	-400	_	_	μΑ	_
"L" level output current	lol	5	_	_	mA	_
⟨Synchronization signal separation	block					
Minimum SYNC separation level	VSMin.	-50	_	50	mVP-P	_
"H" level output voltage	Vон	4.5	5.0	_	V	_
"L" level output voltage	Vol	_	0.2	0.5	V	_
"L" level output current	lol	2	_	_	mA	_
Rise time	TR	_	80	130	ns	_
Fall time	TF	_	30	80	ns	_
Rise delay time	Trd	_	100	150	ns	_
Fall delay time	TFD	_	100	150	ns	_
⟨Control block⟩						-
"H" level input voltage	VIH	1.8	_		V	_
"L" level input voltage	VIL	_	_	1.2	V	_
"H" level input current	Іін	80	100	130	μA	_
"L" level input current	lı∟	-3	-1	_	μΑ	_

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OBH7659FS(Unless otherwise noted, Ta=25°C, Vcc=5.0V)

	ns
\( \text{Min.} \) Typ. Max. \( \text{Kintire device} \) \( \text{Circuit current} \) ICc \( 15 \) 25 \( 35 \) mA \( - \text{Circuit current during power save} \) IPsv \( 7 \) 14 \( 22 \) mA \( PS="H" \)	
Circuit current ICc 15 25 35 mA —  Circuit current during power save IPSV 7 14 22 mA PS="H"	
Circuit current during power save IPSV 7 14 22 mA PS="H"	
⟨R,G,B video SW⟩	
Voltage gain         Gv         -1.0         -0.5         0         dB         f=10MHz	
Interchannel relative gain $\triangle Gvc$ -0.5 0 0.5 dB f=10MHz	
Interblock relative gain $\triangle GVB$ -0.5 0 0.5 dB f=10MHz	
Output dynamic range Vom 2.6 - VP-P f=1kHz	
⟨C-MOS analog SW⟩	
On-resistance Ron - 200 400 $\Omega$ VIN=2.5V	
Interchannel ON resistance differential $\triangle Ron$ — 20 40 $\Omega$ VIN=2.5V	
Interchannel cross talk CT70 -55 dB f=150kHz	
Transmission delay time tb - 20 - ns RL=100 Ω ,CL=50pF	:
⟨Control block⟩	
"H" level voltage VH 3.5 - V -	
"L" level voltage VL — — 1.5 V —	

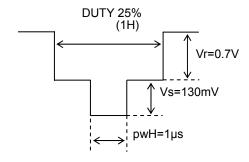
#### Guaranteed design parameters

OBA7657F(Unless otherwise noted, Ta=25°C, Vcc=5.0V)

Decemeter	Cumbal		Limits		Unit	Conditions		
Parameter	Symbol	Min.	Тур.	Max.	Ullit	Conditions		
⟨Analog SW block⟩	⟨Analog SW block⟩							
Input pin cross talk 2	CTI2	_	-30	-15	dB	f=230kHz, VIN=1VP-P		
Interblock cross talk 2	CTB2	_	-30	-15	dB	f=230MHz,Vin=1V <sub>P-P</sub>		
Frequency characteristic	Gf	-6	-3	-1	dB	f=1MHz/230MHz, Vin=1VP-P		
Input pin frequency differential	∆Gfl	-1	0	+1	dB	f=1MHz/100MHz, Vin=1VP-P		
Interblock frequency characteristic differential	ΔGfB	-1	0	+1	dB	f=1MHz/100MHz, VIN=1VP-P		
⟨SYNC separation block⟩								
SYNC separation frequency	fH-R	200	_	_	kHz	Input waveform **1		
SYNC separation pulse width 1	pwH1	3.0	_	_	μs	Input waveform **2 fH=20kHz		
SYNC separation pulse width 2	pwH2	0.5	_	_	μs	Input waveform **2 fH=100kHz		
SYNC separation pulse width 3	pwH3	0.3	_	_	μs	Input waveform **2 fH=200kHz		
SYNC separation level 1	VS1	300	_	_	μs	Input waveform **3 fH=20kHz		
SYNC separation level 2	VS2	100	_	_	μs	Input waveform **3 fH=100kHz		
SYNC separation level 3	VS3	60	_	_	μs	Input waveform **3 fH=200kHz		

<sup>(</sup>Input waveform)

#### Period of horizontal synchronization signal



#### OBH7659FS(Unless otherwise noted, Ta=25°C, Vcc=5.0V)

Parameter	Cumbal	Limits		Unit	Conditions			
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions		
⟨R/G/B video SW⟩								
Frequency characteristics 1	f1	-3.0	0	+1.0	dB	f=50MHz		
Frequency characteristics 2	f2	-6.0	-3	-1.0	dB	f=250MHz		
Interchannel relative frequency characteristics	Δfc	-0.5	0	0.5	dB	f=50MHz		
Interblock relative frequency characteristics	ΔfB	-0.5	0	0.5	dB	f=50MHz		
Interchannel cross talk 1	CTC1	_	-50	-35	dB	f=50kHz		
Interchannel cross talk 2	CTC2	_	-30	-15	dB	f=250MHz		
Interblock cross talk 1	СТв1	_	-50	-35	dB	f=50MHz		
Interblock cross talk 2	CT <sub>B2</sub>	_	-30	-15	dB	f=250MHz		

X1 VS and pwH are variable. VS and pwH are inter-related. See the characteristics diagram.

<sup>※2</sup> VS = 130 mW and pwH are variable.

<sup>3</sup> pwH = 1  $\mu$ s and VS are variable.

#### ●Block diagram ○BA7657F

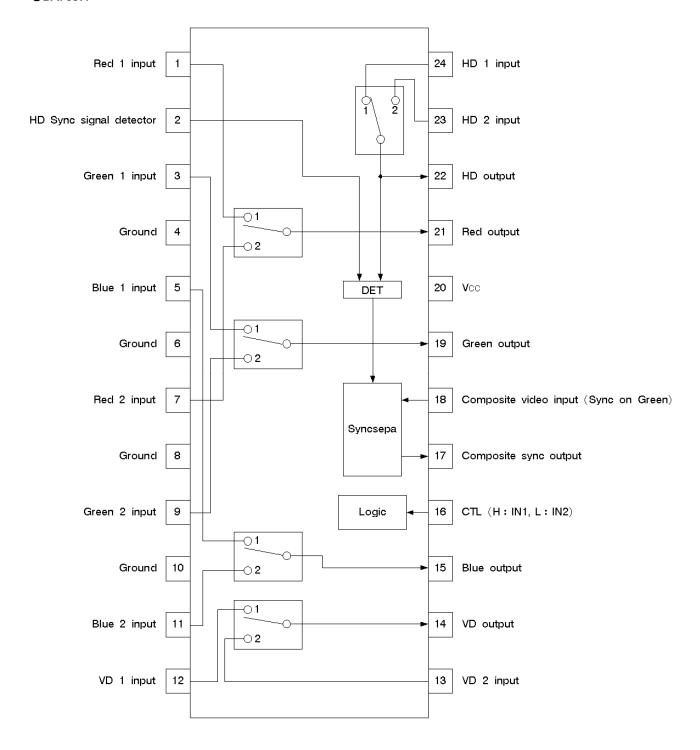


Fig.1

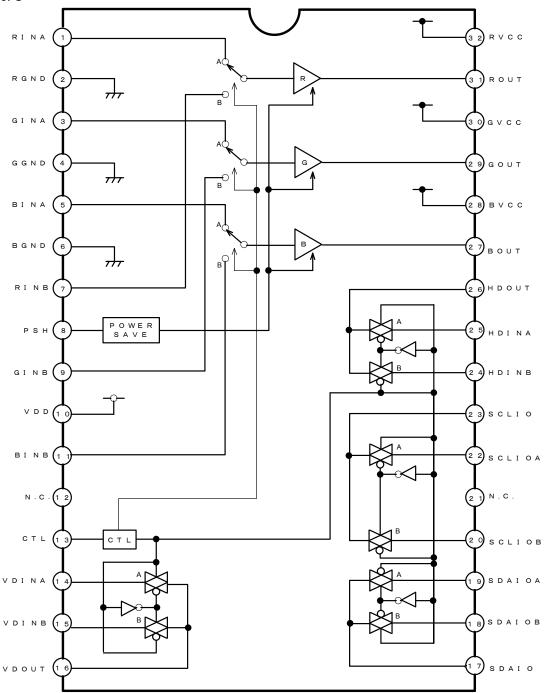


Fig.2

### ●Pin descriptions (BA7657F)

	DBA7657F						
Pin No.	Pin name	Reference potential	Equivalent circuit	Function			
1 3 5 7 9 11	Red1 Input Green1 Input Blue1 Input Red2 Input Green2 Input Blue2 Input	3.7V when selected 0V when not selected	100 6.8k	2-channel switching of R, G, and B signals. Select between: CTL: H input1 CTL: L input2			
15 19 21	Blue output Green output Red output	2.0V	50 ₹ Vcc	Output pins for RGB signals. Insert resistance from 100 to 300 Ω near the pins to suppress f peaks at high frequencies.			
16	Control	H≧1.8V L≦1.2V	Vcc \$35k	CTL pins Select between: CTL: H input1 CTL: L input2			
12 13 23 24	VD1 input VD2 input HD2 input HD1 input	H≧1.8V L≦1.2V	12, 13 23, 24pin	2-channel switching of VD and HD signals. Select between: CTL: H input1 CTL: L input2			
14 22	VD output HD output	Vон≧3.0V Vo∟≦10.5V	2.0k 100 14, 22pin	Output pins for vertical synchronization signal (VD) And horizontal synchronization signal (HD).			

#### **OBA7657F**

OBA765	07F			
Pin No.	Pin name	Reference potential	Equivalent circuit	Function
18	Composite Video input	2.5V	25 k from DET out  18pin	Input pin for composite signal (Sync on Green).
2	HD Sync Signal detector	_	from HD out to sync sepa  Vcc  25k  2pin	This pin is used to detect whether or not the HD signal is being input. When the HD signal is being input, the synchronization signal separation circuit is stopped.
17	Composite sync output	_	17pin	Synchronization signal output pin  Synchronization separation is performed for the input signal from pin 18 if the Hb signal is not being input.
20	Vcc	5V	_	Insert a decoupling capacitor near the pin.
4 6 8	GND	0V	_	Use as large a GND pattern area as possible.

# ●Pin descriptions (BH7659FS) OBH7659FS

Pin NO	Pin name	Reference potential	Equivalent circuit	Function
1 3 5 7 9	R chroma signal input pin A (RINA) G chroma signal input pin A (GINA) B chroma signal input pin A (BINA) R chroma signal input pin B (RINB) G chroma signal input pin B (GINB) B chroma signal input pin B (GINB) B chroma signal input pin B (BINB)	3.5V when selected 0V when not selected	3.7V 10k 2k	RGB signals are switched in two channels. When selected by SW, the DC potential is approximately 3.5V, and when not selected, the DC potential is about 0 V.
27 29 31	B chroma signal input pin (BOUT) G chroma signal input pin (GOUT) R chroma signal input pin (ROUT)	1.85V	500\$ \$ 2k	Power save function is used when PSH pin is set to high level.
8 13	Power save input pin (PSH)  Control input pin (CTL)	0V	3.25V	PSH Pin Power save off ≤1.5V Power save on ≥3.5V  CTL Pin Input A≥3.5V Input B≤1.5V

OBH765	948			<del>_</del>
Pin No.	Pin name	Reference potential	Equivalent circuit	Function
14 15 16	VD signal input pin A (VDINA) VD signal input pin B (VDINB) VD signal output pin (VDOUT)	·	Vpo <b>◆</b>	
17	SDA signal output pin (SDAIO)			
18 19	SDA signal input pin B (SDAIOB) SDA signal input pin A			Vp, Hp, SDA, and SCL are
	(SDAIOA)	0V		switched in two channels. Bidirectional access (I/O) is enabled by the CMOS
20	SCL signal input pin B (SCLIOB) SCL signal input pin A		<del></del>	analog SW.
23	(SCLIOA) SCL signal output pin (SCLIO)			
24 25	HD signal input pin B (HDINB) HD signal input pin A			
26	(HDINA) HD signal output pin			
2	(HDOUT)  R GND pin (RGND)	0V	_	This is the GND pin for the R video SW block.
4	G GND pin (GGND)	0V	_	This is the GND pin for the B video SW block.
6	B GND pin (BGND)	0V	_	This is the GND pin for the G video SW block , C-MOS SW block.
10	C-MOS supply voltage pin (VDD)	5V	_	This is the VDD pin for the C-MOS SW block.
28	B supply voltage pin (BVcc)	5V	_	This is the Vcc pin for the B video SW block
30	G supply voltage pin (GVcc)	5V	_	This is the Vcc pin for the G video SW block
32	R supply voltage pin (RVcc)	5V	_	This is the Vcc pin for the R video SW block

#### Description of operations

#### **OBA7657F**

#### 1) Analog SW block

Two channels of RGB signals can be switched. IN1 can be selected when high-level voltage is applied to the CTL pin, and IN2 can be selected when low level voltage is applied.

#### 2) Digital SW block

This block switches between two channels of HD and VD ynchronization signals. HD and VD synchronization signals are output for IN1 when high-level voltage is applied to the CTL pin, and these signals are output for IN2 when a low-level voltage is applied to the CTL pin.

#### 3) Synchronization signal separation block

This block separates composite signals (Sync on Green) and synchronization signals and outputs positive-electrode composite synchronization signals. When an Hb signal is being input, the synchronization signal detector operates and stops the synchronization signal separation circuit. A low-level output voltage is used for output. The time at which the synchronization signal separation circuit will be stopped can be set using external time constants for the circuit detection pin.

#### I/O relations

Input			Output			
HD	VD	Sync on Green	HD	VD	Composite Sync	
_	_	0	_	_	0	
0	_	0	0	_	_	
_	0	0	_	0	0	
0	0	0	0	0	_	
0	_	_	0	_	_	
_	0	_	_	0	_	
0	0	_	0	0	_	

#### **OBH7659FS**

#### 1) Analog SW block

R, G, and B chroma signals are switched in two channels. INA is selected by applying a high-level voltage to the CTL pin, and INB is selected by applying a low-level voltage. When the power save pin (pin 8) is set to high level, the current to the SW block's output transistors is reduced to lower the circuit current. Even during low power mode, signal switching can be performed normally as long as there is no drop in frequency characteristics.

#### 2) CMOS analog SW block

SDA and SDC signals are switched via an  $I^2C$  bus to handle two channels of HD and VD synchronization signals, and to exchange information bidirectional between a computer and a monitor. The switching circuits used by this IC handle are configured as CMOS analog switches in order to handle  $I^2C$  BUS signals and to transmit input and output signals bidirectional. (ON resistance: Ron 200  $\Omega$  typ.)

# ●Application circuit ○BA7657F

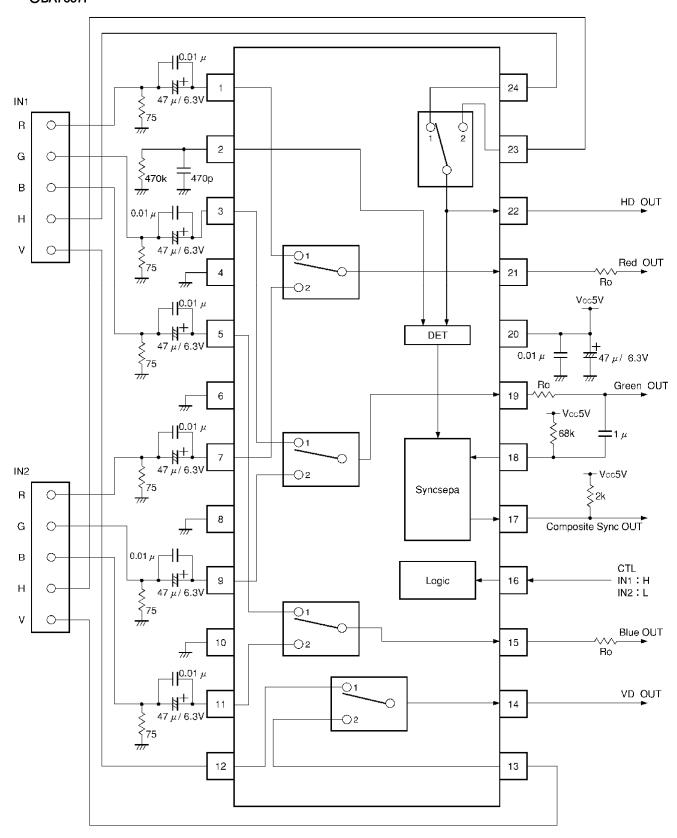


Fig.3

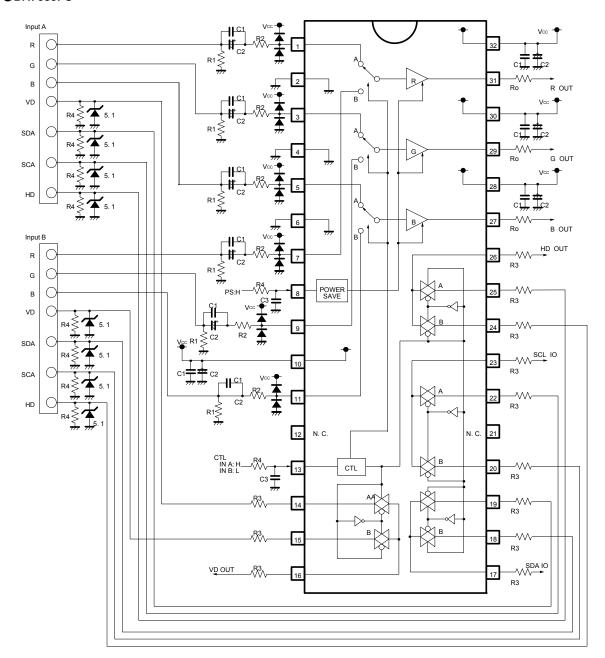


Fig.4

#### ●Reference data OBA7657F

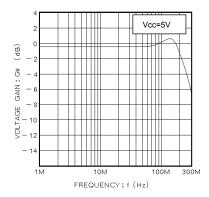


Fig.5 Frequency characteristic

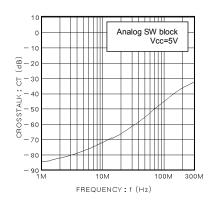


Fig.6 Interchannel crosstalk

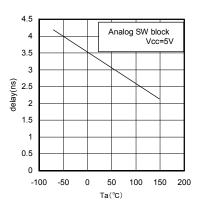


Fig.7 Input/output delay timevs.
Temperatur

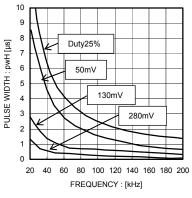


Fig.8 Minimum SYNC separation characteristic

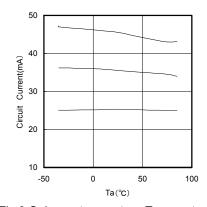


Fig.9 Quiescent current vs. Temperature

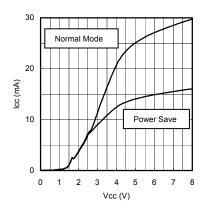


Fig.10 Circuit current vs. Supply voltage

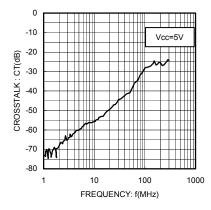


Fig.11 interchannel crosstalk

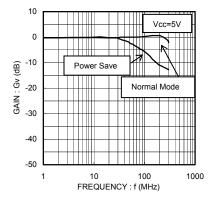


Fig.12 Frequency characteristics

#### Notes for use

#### **OBA7657F. BH7659FS**

- 1) Numbers and data in entries are representative design values and are not guaranteed values of the items.
- 2) Although we are confident in recommending the sample application circuits, carefully check their characteristics further when using them. When modifying externally attached component constants before use, determine them so that they have sufficient margins by taking into account variations in externally attached components and the Rohm LSI, not only for static characteristics but also including transient characteristics.
- 3) Absolute maximum ratings

If applied voltage, operating temperature range, or other absolute maximum ratings are exceeded, the LSI may be damaged. Do not apply voltages or temperatures that exceed the absolute maximum ratings. If you think of a case in which absolute maximum ratings are exceeded, enforce fuses or other physical safety measures and investigate how not to apply the conditions under which absolute maximum ratings are exceeded to the LSI.

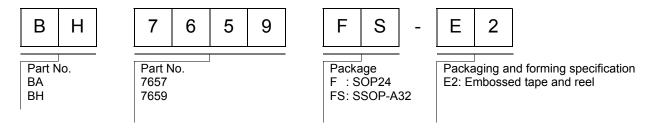
- 4) GND potential
  - Make the GND pin voltage such that it is the lowest voltage even when operating below it. Actually confirm that the voltage of each pin does not become a lower voltage than the GND pin, including transient phenomena.
- Thermal design
  - Perform thermal design in which there are adequate margins by taking into account the allowable power dissipation in actual states of use.
- 6) Shorts between pins and misinstallation
  - When mounting the LSI on a board, pay adequate attention to orientation and placement discrepancies of the LSI. If it is misinstalled and the power is turned on, the LSI may be damaged. It also may be damaged if it is shorted by a foreign substance coming between pins of the LSI or between a pin and a power supply or a pin and a GND.
- Operation in strong magnetic fields
   Adequately evaluate use in a strong magnetic field, since there is a possibility of malfunction.

#### **OBA7657F**

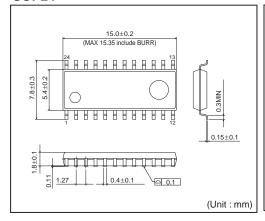
- 8) External resistance for analog SW block
  - The frequency characteristics of analog switches vary according to the output load capacity. Set an external resistance value of R0 to keep frequency characteristics as flat as possible.
- 9) Polarity of input coupling capacitor
  - When this IC is switched, variation is approximately 3.7 V when the input pin's DC voltage has been selected, but is 0 V when the input pin's DC voltage has not been selected. Therefore, the input coupling capacitor's polarity should be set so as to avoid applying a reverse voltage to capacitors, whether the input pin's DC voltage has been selected or not.
- 10) High-frequency characteristics of input coupling capacitor
  - Since this IC handles signals at very high frequencies, when using an electrolytic capacitor as a coupling capacitor for input, be sure to insert high-frequency oriented ceramic capacitors (approximately 0.01 µF) in parallel.
- 11) Layout of target board
  - Since this IC handles signals at very high frequencies, be sure to insert the power supply pin's decoupling capacitor close to the IC's power supply pin. Also, use as large a GND pattern as possible.
- 12) Switching speed
  - Since this IC changes the DC voltage of input pins when switching, some time is required for switching. The amount of switching time can be determined by time constants that are in turn determined by the capacity of the coupling capacitor connected to the input pin, and the IC's internal input resistance. When using the recommended input coupling capacitor whose capacitance is  $47~\mu\text{F}$ , the switching time is approximately 0.5~seconds.

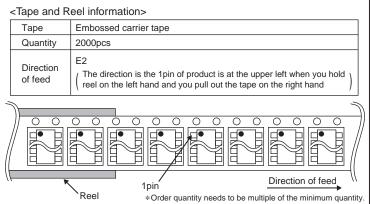
- 13) External resistance for analog SW block
  - The frequency characteristics of analog switches vary according to the output load capacity. Set an external resistance value of R0 to keep frequency characteristics as flat as possible.
- 14) Polarity of input coupling capacitor
  - When this IC is switched, variation is approximately 3.5 V when the input pin's DC voltage has been selected, but is 0 V when the input pin's DC voltage has not been selected. Therefore, the input coupling capacitor's polarity should be set so as to avoid applying a reverse voltage to capacitors, whether the input pin's DC voltage has been selected or not.
- 15) High frequency characteristics of input coupling capacitor
  Since this IC handles signals at very high frequencies, when using an electrolytic capacitor as a coupling capacitor for input, be sure to insert high-frequency oriented ceramic capacitors (approximately 0.01 µF) in parallel.
- 16) Layout of target board
  - Since this IC handles signals at very high frequencies, be sure to insert the power supply pin's decoupling capacitor close to the IC's power supply pin. Also, use as large a GND pattern as possible.

#### Ordering part number

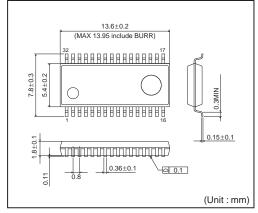


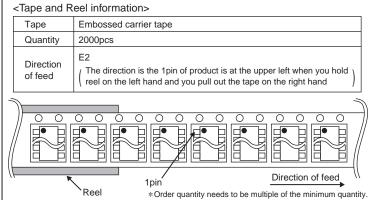
#### SOP24





#### SSOP-A32





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If you intend to export or ship overseas any Product or technology specified herein that may be controlled under the Foreign Exchange and the Foreign Trade Law, you will be required to obtain a license or permit under the Law.



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## ROHM Customer Support System

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